

FIGHTING THE FLOP/BYTE GAP IN SCIENTIFIC COMPUTING By Solving PDES in High order

Alexander Heinecke Parallel Computing Lab, Intel Labs, USA 2016-04-18 Imperial College London, United Kingdom

Legal Disclaimer & Optimization Notice

INFORMATION IN THIS DOCUMENT IS PROVIDED "AS IS". NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO THIS INFORMATION INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

Software and workloads used in performance tests may have been optimized for performance only on Intel microprocessors. Performance tests, such as SYSmark and MobileMark, are measured using specific computer systems, components, software, operations and functions. Any change to any of those factors may cause the results to vary. You should consult other information and performance tests to assist you in fully evaluating your contemplated purchases, including the performance of that product when combined with other products.

Copyright © 2016, Intel Corporation. All rights reserved. Intel, Pentium, Xeon, Xeon Phi, Core, VTune, Cilk, and the Intel logo are trademarks of Intel Corporation in the U.S. and other countries.

Optimization Notice

Intel's compilers may or may not optimize to the same degree for non-Intel microprocessors for optimizations that are not unique to Intel microprocessors. These optimizations include SSE2, SSE3, and SSSE3 instruction sets and other optimizations. Intel does not guarantee the availability, functionality, or effectiveness of any optimization on microprocessors not manufactured by Intel. Microprocessor-dependent optimizations in this product are intended for use with Intel microprocessors. Certain optimizations not specific to Intel microarchitecture are reserved for Intel microprocessors. Please refer to the applicable product User and Reference Guides for more information regarding the specific instruction sets covered by this notice.

Notice revision #20110804

Outline

- Challenges and Settings in current HPC and Intel's Parallel Computing Lab
- High Order Earthquake Simulation SeisSol
- High Order CFD NekBox/Nek5000
- LIBXSMM
- Conclusion

înte

Current & Next Generation Intel[®] Xeon and Xeon Phi[™] Platforms

Xeon*

Latest released – Broadwell (14nm process)

- Intel's Foundation of HPC Performance
- Up to 22 cores, Hyperthreading
- ~66 GB/s stream memory BW (4 ch. DDR4 2400)
- AVX2 256-bit (4 DP, 8 SP flops) -> 0.7 TFLOPS





Xeon Phi*

Knights Landing (Future generation, 14nm process),

- Optimized for highly parallelized compute intensive workloads
- Common programming model & S/W tools with Xeon processors, enabling efficient app readiness and performance tuning
- 60+ cores, 400+ GB/s stream BW, on-die 2D mesh
- AVX512-512-bit (8 DP, 16 SP flops) -> >3 TFLOPS
- https://software.intel.com/en-us/articles/what-disclosures-hasintel-made-about-knights-landing

*Intel Xeon and Intel Xeon Phi are trademarks of Intel Coporation in the US and/or other countries.





Modern HPC....

$$Speedup = \left(\frac{1}{Serial_{frac} + \frac{1 - Serial_{frac}}{NumCores}}\right) * \left(\frac{1}{Scalar_{frac} + \frac{1 - Scalar_{frac}}{VectorLength}}\right)$$

Goal: Reduce Serial Fraction and Reduce Scalar Fraction of Code

Ideal Speedup: NumCores*VectorLength (requires zero scalar, zero serial work)



inte

HPC is hard -> Our Approach at PCL



SeisSol

High Order Earthquake Simulations

http://www.seissol.org

Joint Work with Michael Bader (TUM), Alexander Breuer (TUM, SDSC) This slide deck is based on the ISC'15 paper with an ISC'16 preview

(intel

Motivation

"Development of more realistic implementations of dynamic or kinematic representations of fault rupture, including simulation of higher frequencies (up to 10+ Hz)."

Research Topics in GMP, 2014 Science Collaboration Plan, Southern California Earthquake Center (SCEC).



States for some and the last	A 44 44 1 1	0000			_				
INSTRUMENTAL	1	11-111	IV	V	VI	VII	VIII	LX.	Xe
PEAK VEL.(om/s)	<0.07	0.4	1.9	5.8	11	22	43	83	>160
PEAK ACC.(%g)	«Ø.1	0.5	2.4	6.7	13	24	44	B3	>156
DAMAGE	none	none	none	Very light	Light	Moderate	Mod/Heavy	Heavy	Very Heavy
PERCEIVED SHAKING	Not felt	Weak	Light	Moderate	Strong	Very strong	Severe	Violent	Extreme

ShakeMap, M6.0, 2014-08-24, 3:20 am



Downtown Napa, Aug 24th, 2014. source: cnn.com

Downtown Napa, Nov 28th, 2015.

Seismic Wave Propagation & Dynamic Rupture Simulation



- complex heterogeneous media
- Dynamic Rupture without artificial oscillations
- High order: ADER(time)-DG(space)

- Highly Optimized Compute Kernels
- Massively parallel

'inte

The M7.2 Landers 1992 Earthquake Simulation – Gordon Bell Finalist 14

- 191,098,540 tetrahedrons (~1300 per core of SuperMUC, ~130 per thread of Xeon Phi on Stampede)
- Production run SuperMUC:
 - 234,567 time steps equaling 42s simulated time
 - Output: 23 pick-points + high-res fault
 - 7h 15m @ 147,456 SNB-EP cores
 - 1.25 PFLOPs incl. setup and output!! (96.7% of scaling without setup and output), SuperMUC
 - 2 PFLOPS on Stampede
 - Frequencies up to 10Hz



Taken from a)

Discontinuous Galerkin in a Small Nutshell

- Most-flexible method
- seen as a mixed/hybrid method
 - FEM: polynomial (high-order) approximation within the element
 - FVM: inter-element convection: up winded numerical fluxes
- pretty new: first serious codes in the 2000s, first ever paper on Navier-Stokes with DG (CFD) in 1997.
- Very compact element-centric formulation
- Inter-element communication just across adjacent faces
 - h- and p-refinement simple
 - Unstructured meshes automatically supported
 - Local-Time-Stepping relatively simple
- high-order can lead to GEMM-like/demanding routines (e.g. SeisSol modal basis and Tets)

Deriving SeisSol's Compute Kernels



Taken from talk for a)

ínte

SeisSol's Compute Kernels – Time Kernel



Zero blocks in \widehat{K}^{ξ} , \widehat{K}^{η} and \widehat{K}^{η} lead to zero values in the degrees of freedom Q_k^n

Matrix size is reduced in each recursive step

Zero values in Q_k^n also appear in the multiplications with A_k^* , B_k^* and C_k^*

Typical Matrix sizes of production runs (converge



SeisSol's Compute Kernels – Local Integration

 $Q_{k}^{*,n_{k}+1} = Q_{k}^{n_{k}} + \mathcal{V}_{k}(\mathcal{T}_{k}) - \sum_{i=1}^{n} F_{k,i}^{-}(\mathcal{T}_{k})$

Sparse/Dense Matrix-Matrix multiplications

Typical Matrix sizes of production runs (convergence order 6): 9x9, 56x9, 56x35A priori known sparsity patterns



SeisSol's Compute Kernels – Boundary Kernel



(intel

SeisSol Key Compute Kernels

- Local Integration (partly L1-cache BW bound, linear memory accesses)
 - Consist of time integration, volume integration and local part of boundary integration
 - 9 element local matrices (3 sparse 24NNZ, 4 9x9, 2 56x9) and 10 global matrices (3 40x56, 3 35x56, 4 56x56) (all number for sixth order)
 - Flop/byte approx. 15 (sixth order)
- **Neighbor Integration** (in theory compute bound, irregular memory accesses and higher bandwidth)
 - 10 element local matrices (4 9x9, 6 56x9) and 4 out of 48 global matrices (4 56x56)
 - Flop/byte approx. 7.5 (sixth order)
- Sparse and Dense Matrix Multiplication of small sizes:
 - Due to unstructured meshes we need a prefetching stream that matches the mesh structure (not a regular DGEMM prefetching strategy)
 - Global (irregularly accessed) operators occupy close to 1.5 MB
 - Code generator which hard-wires sparsity patterns
 - → Intel MKL cannot by used, due to blocking and padding overheads. Using MKL instead of our highly tuned kernels results into 1.5-3X speed-down depending on order.
 - → Due to switch between dense and sparse implementations: highest efficiency doesn't correspond to shortest time to solution

'inte

Systems used in our Performance Comparison

- WSM A dual-socket Intel[®] Xeon[®] X5690 server, 12 cores @3.46 GHz, 48 GB of DDR3-1333 memory, 128-bit SSE4.2 vector instruction set, 41 GiB/s memory bandwidth, 166 GFLOPS double precision peak performance, idle power consumption of 160 W and DGEMM power consumption of 350 W.
- SNB A dual-socket Intel[®] Xeon[®] E5-2670 server, 16 cores @2.6 GHz, 128 GB of DDR3-1600 memory, 256-bit AVX vector instruction set, 75 GiB/s memory bandwidth, 333 GFLOPS double precision peak performance, idle power consumption of 100 W and DGEMM power consumption of 280 W.
- HSW A dual-socket Intel[®] Xeon[®] E5-2699 v3 server, 36 cores @1.9 GHz (guaranteed, P0-frequency is 2.3 GHz), 128 GB of DDR4-1866 memory, 256-bit AVX2 vector instruction set, 105 GiB/s (cluster-on-die enabled) memory bandwidth, 1.1 TFLOPS double precision peak performance @1.9 GHz, idle power consumption of 75 W and DGEMM power consumption of 400 W.
 KNC A Intel[®] Xeon PhiTM 5110P coprocessor, 60 cores @1.06 GHz, 8 GB of
- KNC A Intel[®] Xeon PhiTM 5110P coprocessor, 60 cores @1.06 GHz, 8 GB of GDDR5 memory, 512-bit MIC vector instruction set, 150 GiB/s memory bandwidth and 1 TFLOPS double precision peak performance, idle power consumption of 100 W and DGEMM power consumption of 225 W.

Powermeters:

- Watts-Up?: HSW and WSM
- Megware® Clustsafe®: SNB
- micsmc: (software, co-processor only): KNC

inte

Optimized Matrix Kernels – LIBXSMM

• Highly optimized sparse and dense matrix kernels by offline code generation and auto-tuning (publically available):

- WSM SNB HSW WSM SNB HSW 30 1.00 0.83 ਨੂੰ 25 0.67 🗳 20 15 10 0.50 to 0.33 to 0.33 to 10 0.17 🖫 5 0 0.00 3 5 3 2 6 7 2 5 6 7 4 4 convergence order convergence order
- Intel SSE3, AVX, AVX2, KNC, AVX512F

Fig. 1. Double precision GEMM kernel performance for O2 to O7 on WSM, SNB and HSW. DGEMM performance for $B_O \times 9 \times B_O$ shapes (left) and $B_O \times 9 \times 9$ cases (right) is shown. GFLOPS are depicted as bars whereas fraction of peak performance is given by lines. DGEMMs were executed for 10,000 times on a hot L1 cache.

(intel

Regular Convergence Test

- Regular cubic mesh with 5 tets per cube
- Error-Norms: Wave propagation in diagonal direction with periodic boundaries
- Hardware: HSW @ 1.9 GHz
- Convergence: Mesh
 width



Dumbser, Käser: An arbitrary high-order discontinuous Galerkin method for elastic waves on unstructured meshes – II. The threedimensional isotropic case

What are the benefits from using a higher-order method?





What does this mean for the energy consumption?



Fig. 3. L^{∞} -error of variable σ^{yz} in dependency of the consumed energy for the HSW machine in single- and double-precision.

Benchmark	@1.2 GH	Iz	$@1.9\mathrm{GHz}$		
	Performace	Power	Performace	Power	
STREAM - Triad	$105{ m GiB/s}$	$295\mathrm{W}$	$105{ m GiB/s}$	$345\mathrm{W}$	
DGEMM - $60k \times 60k \times 192$	$610\mathrm{GFLOPS}$	$250\mathrm{W}$	$950\mathrm{GFLOPS}$	$400\mathrm{W}$	

HSW: Dual -socket Xeon E5-2699v3, @1.9 GHz

inte

What reduction in error is possible in a given energy-budget?



Fig. 4. Error with respect to a 150 kJ energy-budget for all matching settings. Shown is the interpolated L^{∞} -error of variable σ^{yz} for the different architectures, orders of convergence and single- and double-precision.

'inte

The LOH.1 Benchmark



 computational domain extending [-15km, 15km]^2 X [0km, 17km]

- free-surface boundary conditions on the surface and outflow boundary conditions everywhere else. 386,518 elements and is unstructured
- the seismic source is located at (0,0,-2000). Shown is a only a part of size [-2km, 15km]^2 X [0,17 km]

Fig. 5. Setup of the LOH.1 scenario.



Fig. 6. Comparison of the vertical particle velocity w at receiver nine. Shown is the reference solution of the SISMOWINE project against Seissol using O2 and O7.

GFLOPS for LOH.1



→ Switching to newer and denser platforms, the memory bound to compute bound ratios increase in higher convergence orders.

MFLOPS/W for LOH.1



→ In case of lower order runs, the lowest frequency results in the best energy to performance ratio (recall micro benchmark results!)

Power Consumption in dependence on the VEX on Haswell



Fig. 8. GFLOPS (left) and the MFLOPS per Watt (right) over all convergences orders and instructions set on HSW @1.9 GHz.

- Shorter vectors result in less performance and less power \rightarrow good for old code
- FMA significantly increases power efficiency

 \rightarrow whenever we can, we should use long vectors and FMA

What are Architectural Learnings?

- Low-order energy consumption: memory-bound new architectures minor impact: 2X Westmere to Haswell.
- High-order energy consumption: >10X Westmere to Haswell. 10^5 better than low-order.
- Very good perf./watt, however: up to 50% useless work!
- Westmere -> Haswell: 14 sparse matrices reduced to 2
 - Vector Performance vs. L1 bandwidth
 - Using gather/scatter or sparsity code gen. turn DGEMMs in to sparse DGEMMs which are an L1 bandwidth benchmark: 2 reads, 1 store per cycle
 - Max. 50% peak since 2nd FPU is empty
 - 50% is not reachable due to address calc. and jumps -> ~25-30% achieved in practice
- Lots of opportunities for architectural or algorithmic (UQ) improvements
- For best time-to-solution, we also need tricks such as LTS

Nek5000 / NekBox

High Order CFD Simulations

http://nek5000.mcs.anl.gov/

https://github.com/maxhutch/nek

Joint Work with Maxwell Hutchinson (U Chicago), David Keyes (KAUST)

ISC'16 paper preview

(intel

Nek Overview

Nek solves the incompressible Navier Stokes equations:

$$\frac{\partial u}{\partial t} + u \cdot \nabla u = -\frac{1}{\rho} \nabla p + \nu \nabla^2 u + f \qquad \nabla \cdot u = 0$$

Incl. advection-diffusion equations for scalar variables such as temperature or mass fractions.

Nek use the spectral element method (SEM) which is a two-level discretization:

- a) A tensor product construction of Gauss-Lobatto-Legendre (GLL) quadrature points within each element -> N^3 DOFs per element
- b) Continuity across elements -> forming a mesh

Operators are written as element local operators:

$$A = (A_x \times I_y \times I_z) + (I_x \times A_y \times I_z) + (I_x \times I_y \times A_z)$$

And direct stiffness summation ensure continuity. Furthermore, this reduces the complexity form $O(N^{6})$ to $O(N^{4})$.

NekBox's main compute routines

A typical NekBox run spends <1% in sparse computations & communications, ~40% in vector-vector or matrix-vector operations, ~60% matrix-matrix operations.

Helmholtz operator:

```
Hu(:,:,:) = gx(:,:,:) * matmul(Kx(:,:), reshape(u, (/N, N*N/)))
do i = 1, n
Hu(:,:,i) += gy(:,:,i) * matmul(u(:,:,i), KyT(:,:))
enddo
Hu(:,:,:) += gz(:,:,:) * matmul(reshape(u, (/N*N, N/)), KzT(:,:))
Hu(:,:,:) = h1 * Hu(:,:,:) + h2 * M(:,:,:) * u(:,:,:)
```

Basis transformation:

```
tmp_x = matmul(Ax, u)
do i = 1, n
    tmp_y(:,:,i) = matmul(tmp_x(:,:,i), AyT)
enddo
    v = matmul(tmp_y, AzT)
Gradient calculation:
    dudx = matmul(Dx, u)
    do i = 1, n
        dudy(:,:,i) = matmul(u(:,:,i), DyT)
    enddo
```

dudz = matmul(u, DzT)



Helmholtz Operator / Basis Transformation



Performance of the Helmholtz operator reproducer (up) and Basis Transformation (bottom) using different implementation for the small matrix multiplications. NTS denotes the usage of non-temporal stores. Measured on Shaheen (32 cores of HSW-EP, 2.3 GHz)

(intel

Some Early High Order Efficiency Results

We model the single-mode Rayleigh-Taylor Instability (Boussinesq equations)



Log-base 10 error of bubble height and mix volume:

$$H = \sup\left\{z : \min_{x,y} T(x, y, z) < T_0\right\} \qquad \Theta = \int |T - T_0| \, dV$$

on Shaheen.

We can see that high orders are favorable as they better match modern hardware and have superior convergence speed.

'inte

LIBXSMM

Library for small matrix multiplications on Intel Architecture

https://github.com/hfp/libxsmm

Joint Work with Hans Pabst (Intel), Greg Henry (Intel)

Abstract and Motivation

"Improving Performance for Small GEMM Size Problems."

- Problem size is characterized by the M, N, and K parameters
 - Common building block for high order methods
 - Common building block for blocked Sparse Linear Algebra
- A suitable problem size may fall within (M N K)^(1/3) <= 60
 - Intel® Math Kernel Library (Intel® MKL) uses MKL_DIRECT_CALL
 - These sizes are smaller than regular S/DGEMM blocked macro-kernels, therefore MKL_DIRECT_CALL helps, but is only the tip of the iceberg- a lot more performance is necessary/possible

LIBXSMM

Interface (C/C++ and FORTRAN API)

Simplified interface for matrix-matrix multiplications

• $c_{m \times n} = c_{m \times n} + a_{m \times k} * b_{k \times n}$ (also full xGEMM)



License

• Open Source Software (BSD 3-clause license)*

* https://github.com/hfp/libxsmm

LIBXSMM Implementation

Three Critical Parts of Technology:

- Highly efficient Frontend (Hans Pabst)
 - BLAS compatible (DGEMM, SGEMM) (even LD_PRELOAD)
 - Support for F77, C89, F2003, C++
 - 2-level code caching
 - Zero-overhead calls into assembly
- Code Generator (Alex Heinecke)
 - Supports all Intel Architectures since 2005, special focus on AVX-512
 - Prefetching across small GEMMs
 - Can generate *.s, inline assembly into *.h/*.c of the feed the JIT encoder
- JIT (Just-In-Time) Encoder (Greg Henry)
 - Encodes an instruction based on basic blocks
 - Very fast as no compilation is involved

JIT overhead (incl. OS overheads)

Xeon E5-2697v4 - JIT compile time in microseconds

- · · Xeon E5-2697v4 - JIT compile time in MKL calls



inte

LIBXSMM Performance on 1c Xeon E5-2697v4 (BDX)

LIBXSMM, static
 Intel MKL 11.3.2, direct-call
 Eigen-3.3-beta1, ICC 16.0.2, dynamic
 Eigen-3.3-beta1, GCC 4.9.2, dynamic
 BLAZE 2.6, ICC 16.0.2, dynamic
 BLAZE 2.6, GCC 4.9.2, dynamic

LIBXSMM, JIT
Eigen-3.3-beta1, ICC 16.0.2, static
Eigen-3.3-beta1, GCC 4.9.2, static
BLAZE 2.6, ICC 16.0.2, static
BLAZE 2.6, GCC 4.9.2, static
PEAK



inte

LIBXSMM vs. MKL DGEMM_BATCH 2x Xeon E5-2697v4 (BDX)

BDX - LIBXSMM

BDX - MKL 11.3.2 (BATCHED)

- · - BDX - LIBXSMM bandwidth



intel

Conclusion and Future/Current Work



Conclusions

- High order simulations can leverage both memory bandwidth and compute
- Due to faster convergence, they are more energy efficient
- Problem solved?
- No!
 - We need a better understanding where these techniques are applicable and where possible traps are.
 - We still need optimal hardware, SeisSol & Nek!
- Therefore:
 - We started a collaboration with U Chicago/ ANL on Nek5000 -> first results have been submitted to ISC'16 and SC'16
 - And of course we are looking for more ©

